

5mmx16mm LIGHT BAR

Part Number: L-845/3YDT

Yellow

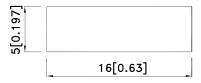
Features

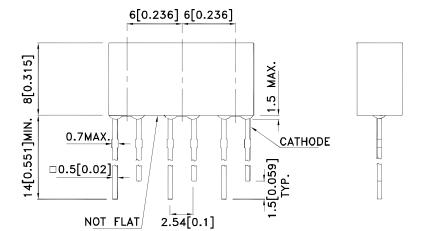
- Uniform light emitting area.
- Easily mounted on P.C. boards or industry standard sockets.
- Flush mountable.
- Excellent on/off contrast.
- Can be used with panels and legend mounts.
- Mechanically rugged.
- Bottom surface of epoxy is not flat.
- RoHS compliant.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions





- All dimensions are in millimeters (inches).
 Tolerance is ±0.25(0.01") unless otherwise noted.
- The state of the state of

SPEC NO: DSAE4445 APPROVED: WYNEC

REV NO: V.7 CHECKED: Allen Liu DATE: MAR/24/2012 DRAWN: D.M.Su

PAGE: 1 OF 6 ERP: 1101007785

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
L-845/3YDT	Yellow (GaAsP/GaP)	Yellow Diffused	3	6	120°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	l==20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	I==20mA
lR	Reverse Current	Yellow		10	uA	VR = 5V

- Notes: 1. Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

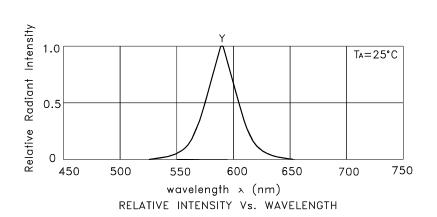
Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

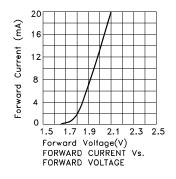
Notes:

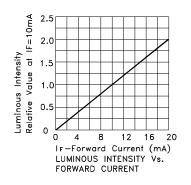
- 1/10 Duty Cycle, 0.1ms Pulse Width.
 2mm below package base.
 5mm below package base.

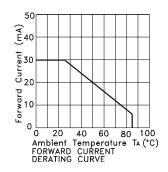
SPEC NO: DSAE4445 **REV NO: V.7** DATE: MAR/24/2012 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: D.M.Su ERP: 1101007785

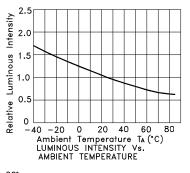


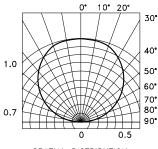
Yellow L-845/3YDT







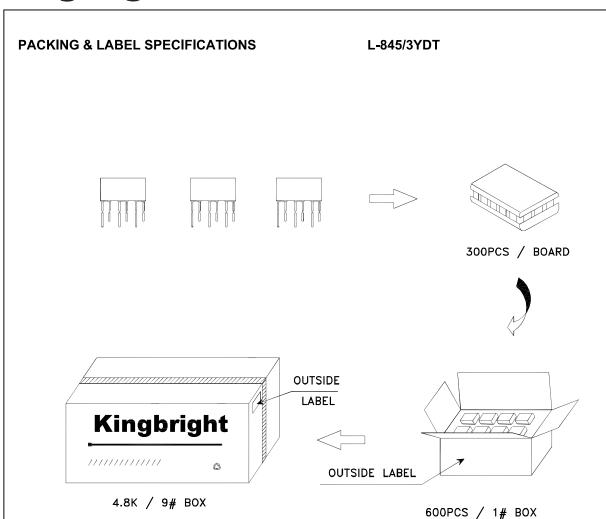


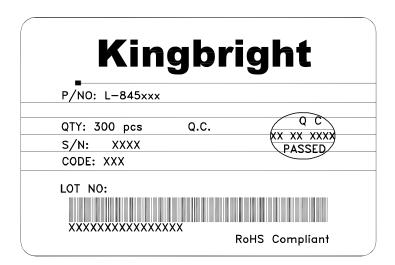


SPATIAL DISTRIBUTION

SPEC NO: DSAE4445 APPROVED: WYNEC REV NO: V.7 CHECKED: Allen Liu DATE: MAR/24/2012 DRAWN: D.M.Su PAGE: 3 OF 6

ERP: 1101007785

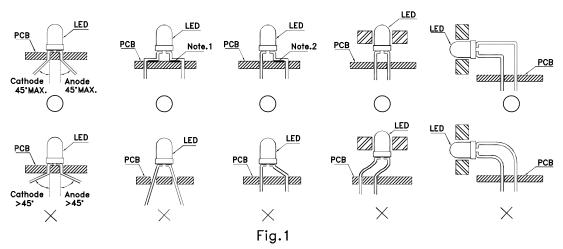




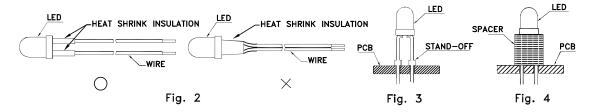
SPEC NO: DSAE4445 APPROVED: WYNEC REV NO: V.7 CHECKED: Allen Liu DATE: MAR/24/2012 DRAWN: D.M.Su PAGE: 4 OF 6 ERP: 1101007785

PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



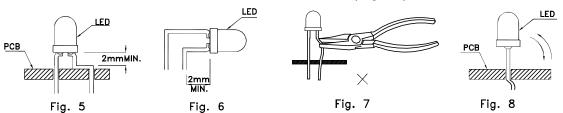
- " \bigcirc " Correct mounting method "imes" Incorrect mounting method
- 2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig.2)
- 3. Use stand—offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



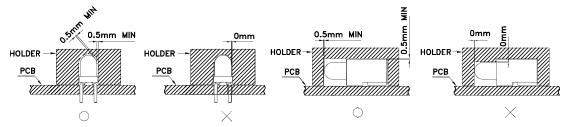
- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

SPEC NO: DSAE4445 APPROVED: WYNEC REV NO: V.7 CHECKED: Allen Liu DATE: MAR/24/2012 DRAWN: D.M.Su PAGE: 5 OF 6 ERP: 1101007785

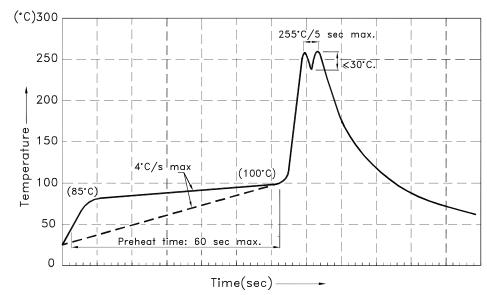
6. Do not bend the leads more than twice. (Fig. 8)



7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 8. The tip of the soldering iron should never touch the lens epoxy.
- 9. Through—hole LEDs are incompatible with reflow soldering.
- 10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 11. Recommended Wave Soldering Profiles:



Notes:

- 1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process. 5.SAC 305 solder alloy is recommended.

PAGE: 6 OF 6

ERP: 1101007785

6.No more than one wave soldering pass.

SPEC NO: DSAE4445 REV NO: V.7 DATE: MAR/24/2012
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: D.M.Su